

Copper

SLOTOCOUP SF 40

Copper SLOTOCOUP SF 40 is used for the production of HDI printed circuit boards in order to achieve superfilling of blind microvias in one process step and copper plating of through holes at the same time especially for mSAP applications (modified semi-additive process).

Copper SLOTOCOUP SF 40 deposits are bright coatings with outstanding levelling quality and excellent metal distribution. The electrolyte was particularly designed for operation in vertical continuous plating lines.

The metal distribution can be adapted to the printed circuit board's surface geometry by regulation of the current density and electrolyte composition.

Copper SLOTOCOUP SF 40 is made-up with three liquid additives.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

